



i3 Microsystems is honored to be invited as a panelist to join discussions on “Secure Heterogeneous Packaging” at the IEEE International PAINE 2021 conference. PAINE is mainly focused around physical device assurance and inspection of electronics for improving hardware security.

The panel will be on **November 30, 14:15-15:30 ET** and in a fully online virtual format. The Secure Heterogeneous Packaging panel will include the following participants:

Panelists:

Dr. Darren Crum (Navy)

Peter O’Donnell (Army)

Dan Toohey (Mercury)

John Stephens (Raytheon)

Brian Sapp (I3 Microsystems)

Moderator:

Saverio Fazzari (DARPA)

Find the full list of featured conference speakers in the following link:

<https://paine-conference.org/speakers-2021/>

Find the full PAINE Program here:

<https://paine-conference.org/program-2021/>